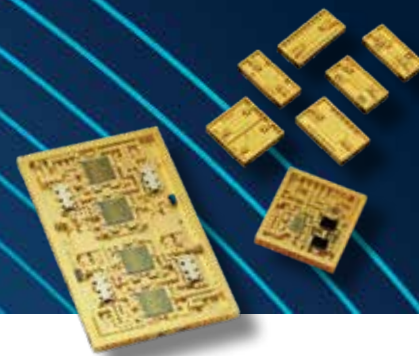


PolyStrata® Standard & Device Specific Packages



Nuvotronics introduces a state-of-the-art, low-loss MMIC package featuring its PolyStrata technology. Designed to complement integrated MMIC performance, the package can be surface mounted to a PCB using standard SMT processes—streamlining manufacturing while delivering superior performance in a more compact form factor than traditional packaging substrates.

Features and Benefits

- Ultra-Low Loss
- Ideal thermal performance due to solid copper construction
- Chip interface compatible with automated Au wire bonding
- PCB interface compatible with standard SMT processes

Applications

- Military
- Space
- Communications
- Instrumentation

Learn More



Standard mmWave Packages

Part Number	Lid	Single Sided Transition Performance			Max Die Size			Package Size			DC Pins	Lead Time jg!opuljo!tupdl*
		Max Frequency (GHz)	Insertion Loss (dB)	Return Loss (dB)	X (mm)	Y (mm)	Z (mm)	X (mm)	Y (mm)	Z (mm)		
PSP1028104	1028940-007	95	0.65	12	5.71	5.55	0.1	9	9	0.7	16	13 weeks
PSP1028105	1028940-006	95	0.65	12	4.71	4.55	0.1	8	8	0.7	14	13 weeks
PSP1028106	1028940-005	95	0.65	12	3.71	3.55	0.1	7	7	0.7	12	13 weeks
PSP1028107†	1028940-004	95	0.65	12	2.71	2.55	0.1	6	6	0.7	12	13 weeks
PSP1028108†	1028940-003	95	0.65	12	1.71	1.55	0.1	5	5	0.7	8	13 weeks
PSP1028109†	1028940-005	50	0.3	12	5	5	0.1	7	7	0.4	12	9 weeks
PSP1028110	1028940-004	50	0.3	12	4	4	0.1	6	6	0.4	10	9 weeks
PSP1028111†	1028940-003	50	0.3	12	3	3	0.1	5	5	0.4	8	9 weeks
PSP1028112†	1028940-002	50	0.3	12	2	2	0.1	4	4	0.4	6	9 weeks
PSP1028113	1028940-001	50	0.3	12	1	1	0.1	3	3	0.4	4	9 weeks

† Samples available

Device Specific mmWave Packages

Part Number	Matching Device	Manufacturer	Package Size			Lid #	Lead Time
			X	Y	Z		
PSP1025530_002	ALP302	Northrop Grumman	6.34	3.869	1.513	1025503	13 weeks
PSP1029439	TGA2962	Qorvo	5.5	6	1.425	1028940-009	9 weeks